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Abstract:

The invention relates to a wire saw for cutting wafers from a workpiece, having a saw head in which at least two wire-guiding rollers are mounted rotatably in each case between a moveable bearing and a fixed bearing, adjacent wire-guiding rollers, together with a wire wound around them, forming a wire frame. Each wire-guiding roller and the moveable bearing and fixed bearing assigned to it form a wire-guiding-roller unit, which can only be removed from the saw head as an entire unit. The invention also relates to a fitting station and to a maintenance and running-in station for the wire-guiding-roller unit and to a method of exchanging the wire-guiding-roller unit.

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